



Document	Document Number	Revision	Date
Spec Sheet	FLB016074A01	I	02-Nov-2019

Band Pass Filter

P/N : FLB016074A01

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Revision	Description	Date
A	Initial Release	19-Oct-2018
B	Soldering Profile Added	24-Oct-2018
C	Dimensions Changed	26-Oct-2018
D	Test Data Added	02-Jan-2018
E	Specification Updated	20-Feb-2019
F	Specification Confirmed	23-Feb-2019
G	Specification Updated	27-Feb-2019
H	Handling Power Added	10-Oct-2019
I	Recommended Land Pattern Added	02-Nov-2019

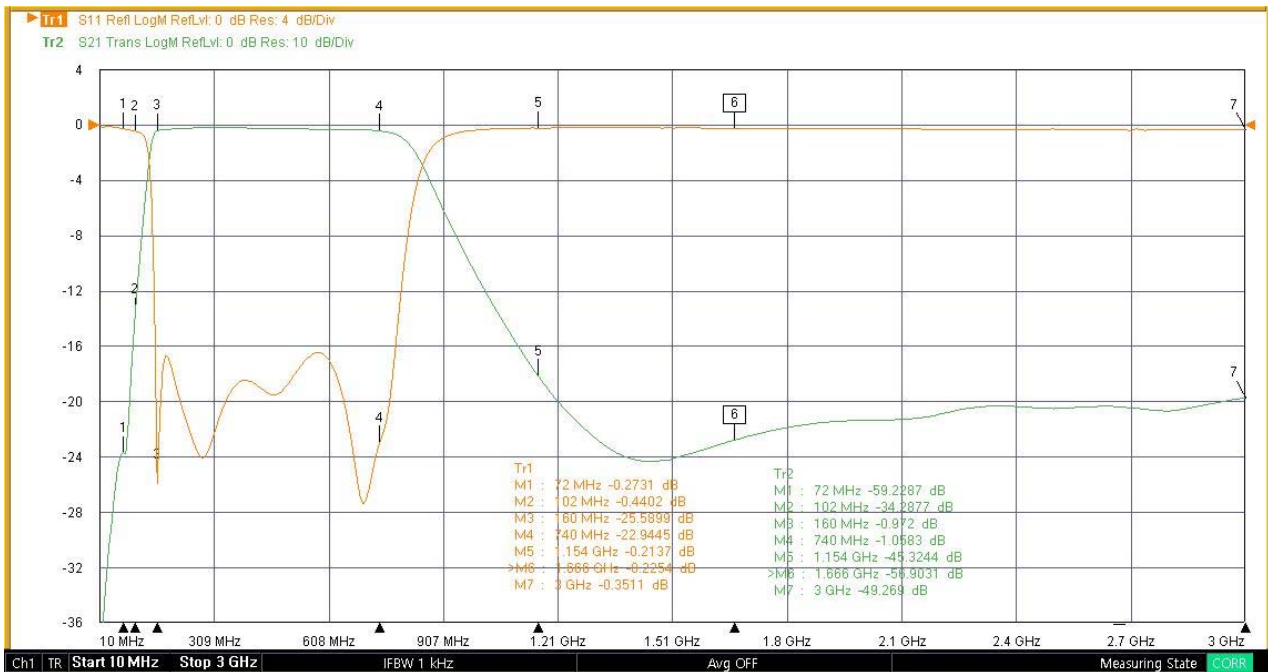


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1. Electrical Specifications

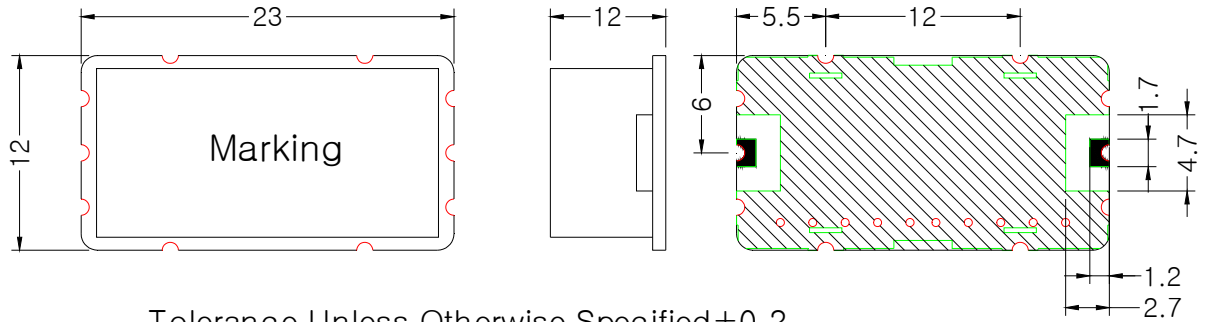
Parameter	Specification	Remarks
Pass Band	160MHz ~ 740MHz	
Insertion Loss	1.2dB max.	
Return Loss	15dB min.	
Ripple	1.0dB max.	
Attenuation	30.0dB min @ 102MHz	
	30.0dB min @ 1154MHz	
	50.0dB min @ DC ~ 72MHz	
	45.0dB min @ 1666MHz ~ 3000MHz	
Power Handling	2.0W(Avg.)	
Input Output Impedance	50Ω	
Operation Temperature Range	-40°C ~ +85°C	

3. Test Data



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4. Mechanical Specification



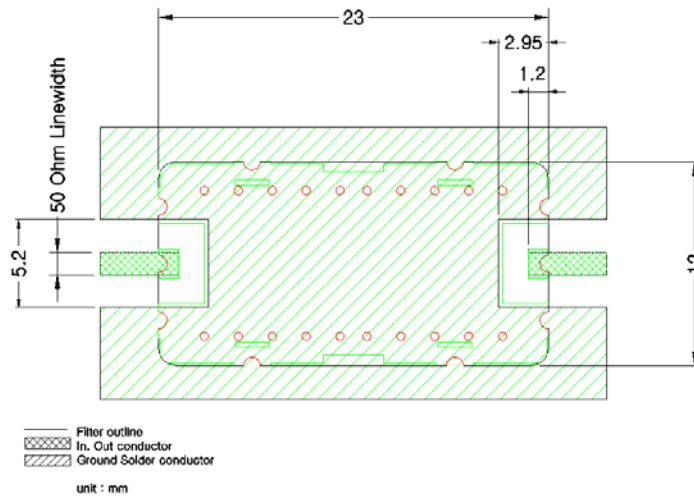
Tolerance Unless Otherwise Specified ± 0.2

Unit mm

■ Port

▨ GND

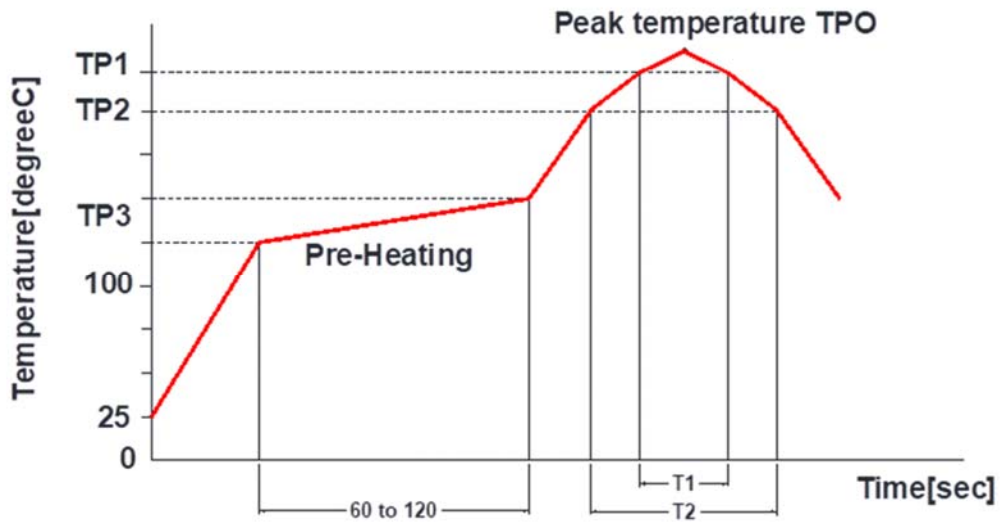
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Parameter	Specification
Dimension	12.0*23.0*12.0 (Unit : mm)

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5. Soldering Profile



Measuring poin of temperature:IN-OUT Terminals of The Device

Reflow Soldering:Both Convection and Infrared Rays ,Hot Air and Hot Plate

Reflow standard condition	TP0(℃)	TP1(℃)	T1(a)	TP2(℃)	T2(a)	TP3(℃)
Sn-3Ag-0.5 solder	245 +/- 5	220	30 to 60	-	-	150 to 180
Test condition of reflowheat resistance	260+5/- 0	240	20	220	70	150 to 180